

### Product Overview

NSi8210 is a high reliability single channel digital isolator. The NSi8210 device is safety certified by UL1577 support several insulation withstand voltages (3.75kVrms, 5kVrms), while providing high electromagnetic immunity and low emissions at low power consumption. The data rate of NSi8210 is up to 150Mbps, and the common-mode transient immunity (CMTI) is up to 200kV/us. NSi8210 provides default output level configuration when the input power is lost. Wide supply voltage of NSi8210 supports to connect with most digital interface directly, easy to do the level shift. High system level EMC performance enhance reliability and stability of use. AEC-Q100 (Grade 1) option is provided for all devices.

### Key Features

- Up to 5000V<sub>rms</sub> Insulation voltage
- Data rate: DC to 150Mbps
- Power supply voltage: 2.5V to 5.5V
- All devices are AEC-Q100 qualified
- High CMTI: 200kV/us
- Chip level ESD: HBM: ±8kV
- Interlock function
- High system level EMC performance:
  - Enhanced system level ESD, EFT, Surge immunity
- Default output high level or low level option
- Isolation surge voltage: >10kV
- Low power consumption: 1.5mA/ch (1 Mbps)
- Low propagation delay: <15ns
- Operation temperature: -40°C~125°C
- RoHS-compliant packages:
  - SOP8 narrow body
  - SOW8 wide body
  - SOW16 wide body

### Safety Regulatory Approvals

- UL recognition: up to 5000V<sub>rms</sub> for 1 minute per UL1577
- CQC certification per GB4943.1-2011
- CSA component notice 5A approval IEC60950-1 standard
- DIN VDE V 0884-11:2017-01

### Applications

- Industrial automation system
- Isolated SPI, RS232, RS485
- General-purpose multichannel isolation
- Motor Control

### Device Information

| Part Number     | Package | Body Size        |
|-----------------|---------|------------------|
| NSI8210Nx-XSPR  | SOP8    | 4.90mm × 3.90mm  |
| NSI8210Wx-XSWVR | SOW8    | 5.85mm × 7.50mm  |
| NSI8210Wx-XSWR  | SOW16   | 10.30mm × 7.50mm |

### Functional Block Diagrams

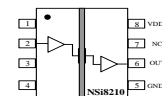


Figure 1. NSI8210Nx-XSPR Block Diagram

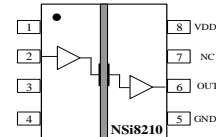


Figure 2. NSI8210Wx-XSWVR Block Diagram

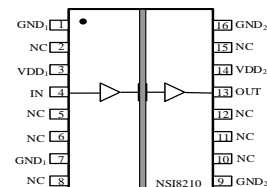


Figure 3. NSI8210Wx-XSWR Block Diagram

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## 1. Pin Configuration and Functions

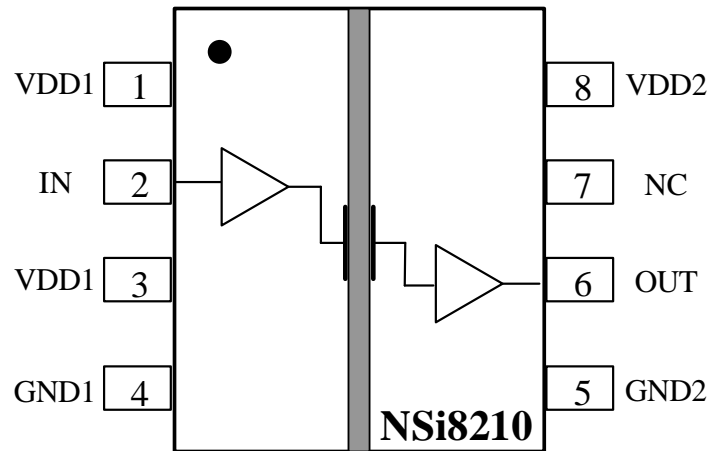


Figure 1.1 NSi8210N Package

Table 1.1 NSi8210N Pin Configuration and Description

| <i>NSi8210N PIN NO.</i> | <i>SYMBOL</i> | <i>FUNCTION</i>                                    |
|-------------------------|---------------|--|
| 1                       | VDD1          | Power Supply for Isolator Side 1                   |
| 2                       | IN            | Logic Input  |
| 3                       | VDD1          | Power Supply for Isolator Side 1                   |
| 4                       | GND1          | Ground 1, the ground reference for Isolator Side 1 |
| 5                       | VDD2          | Power Supply for Isolator Side 2                   |
| 6                       | NC            | Not connect pin; it has no internal connection     |
| 7                       | OUT           | Logic Output                                       |
| 8                       | GND2          | Ground 2, the ground reference for Isolator Side 2 |

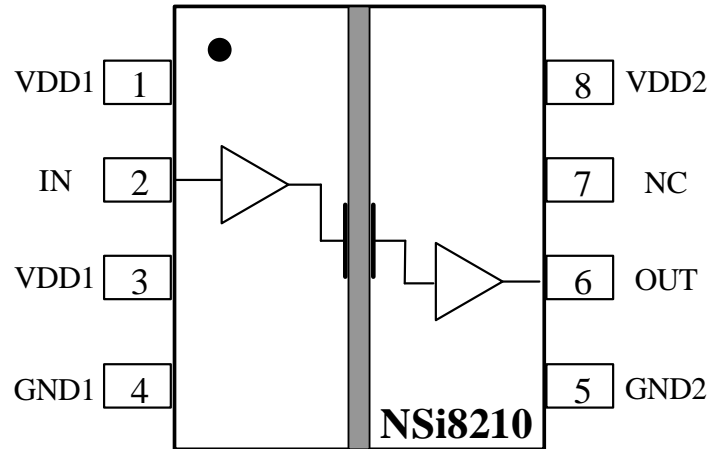


Figure 1.1 NSi8210W SOW8 Package

Table 1.1 NSi8210W SOW8 Pin Configuration and Description

| <i>NSi8210W PIN NO.</i> | <i>SYMBOL</i> | <i>FUNCTION</i>                                    |
|-------------------------|---------------|--|
| 1                       | VDD1          | Power Supply for Isolator Side 1                   |
| 2                       | IN            | Logic Input  |
| 3                       | VDD1          | Power Supply for Isolator Side 1                   |
| 4                       | GND1          | Ground 1, the ground reference for Isolator Side 1 |
| 5                       | VDD2          | Power Supply for Isolator Side 2                   |
| 6                       | NC            | Not connect pin; it has no internal connection     |
| 7                       | OUT           | Logic Output                                       |
| 8                       | GND2          | Ground 2, the ground reference for Isolator Side 2 |

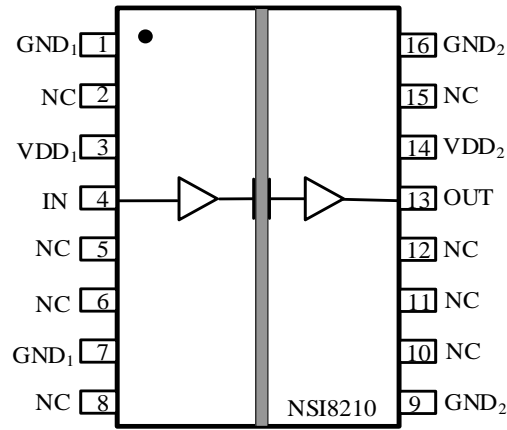


Figure 1.1 NSi8210W SOW16 Package

Table 1.1 NSi8210W SOW16 Pin Configuration and Description

| <i>NSi8210W PIN NO.</i> | <i>SYMBOL</i> | <i>FUNCTION</i>                                    |
|-------------------------|---------------|--|
| 1                       | GND1          | Ground 1, the ground reference for Isolator Side 1 |
| 2                       | NC            | Not connect pin; it has no internal connection     |
| 3                       | VDD1          | Power Supply for Isolator Side 1                   |
| 4                       | IN            | Logic Input  |
| 5                       | NC            | Not connect pin; it has no internal connection     |
| 6                       | NC            | Not connect pin; it has no internal connection     |
| 7                       | GND1          | Ground 1, the ground reference for Isolator Side 1 |
| 8                       | NC            | Not connect pin; it has no internal connection     |
| 9                       | GND2          | Ground 2, the ground reference for Isolator Side 2 |
| 10                      | NC            | Not connect pin; it has no internal connection     |
| 11                      | NC            | Not connect pin; it has no internal connection     |
| 12                      | NC            | Not connect pin; it has no internal connection     |
| 13                      | OUT           | Logic Output                                       |
| 14                      | VDD2          | Power Supply for Isolator Side 2                   |
| 15                      | NC            | Not connect pin; it has no internal connection     |
| 16                      | GND2          | Ground 2, the ground reference for Isolator Side 2 |

## 2. Absolute Maximum Ratings

| Parameters                         | Symbol            | Min  | Typ | Max     | Unit | Comments  |
|------------------------------------|-------------------|------|-----|---------|------|---|
| Power Supply Voltage               | VDD1, VDD2        | -0.5 |     | 6.5     | V    |   |
| Maximum Input Voltage              | IN                | -0.4 |     | VDD+0.4 | V    | The maximum voltage must not exceed 6.5V  |
| Maximum Output Voltage             | OUT               | -0.4 |     | VDD+0.4 | V    | The maximum voltage must not exceed 6.5V  |
| Maximum Input/Output Pulse Voltage | IN, OUT           | -0.8 |     | VDD+0.8 | V    | Pulse width should be less than 100ns, and the duty cycle should be less than 10% |
| Output current                     | Io                | -15  |     | 15      | mA   |   |
| Maximum Surge Isolation Voltage    | V <sub>IOSM</sub> |      |     | 6.25    | kV   | V <sub>TEST</sub> =V <sub>IOSM</sub> ×1.6   |
| Operating Temperature              | Topr              | -40  |     | 125     | °C   |   |
| Storage Temperature                | Tstg              | -40  |     | 150     | °C   |   |
| Electrostatic discharge            | HBM               |      |     | ±8000   | V    |   |
|                                    | CDM               |      |     | ±2000   | V    |   |

## 3. Recommended Operating Conditions

| Parameters               | Symbol     | Min | Typ | Max | Unit | Comments |
|--------------------------|------------|-----|-----|-----|------|----------|
| Power Supply Voltage     | VDD1, VDD2 | 2.5 |     | 5.5 | V    |          |
| High-level Input Voltage | VIH        | 2   |     |     | V    |          |
| Low-level Input Voltage  | VIL        |     |     | 0.8 | V    |          |
| Data Rate                | DR         | 0   |     | 150 | Mbps |          |
| Ambient Temperature      | Ta         | -40 |     | 125 | °C   |          |

## 4. Thermal Information

| Parameters                                | Symbol              | SOW16 | SOW8 | SOP8  | Unit  |
|---|---------------------|-------|------|-------|-------|
| IC Junction-to-Air Thermal Resistance     | $\theta_{JA}$       | 94.4  | 84.3 | 146.1 | ° C/W |
| Junction-to-case (top) thermal resistance | $\theta_{JC (top)}$ | 57.3  | 36.3 | 63.1  | ° C/W |
| Junction-to-board thermal resistance      | $\theta_{JB}$       | 57.1  | 47.0 | 80.0  | ° C/W |

## 5. Specifications

### 5.1. Electrical Characteristics

| Parameters                     | Symbol              | Min     | Typ  | Max | Unit  | Comments   |
|--------------------------------|---------------------|---------|------|-----|-------|--|
| Power on Reset                 | VDD <sub>POR</sub>  |         | 2.2  |     | V     | POR threshold as during power-up                       |
|                                | VDD <sub>HYS</sub>  |         | 0.1  |     | V     | POR threshold Hysteresis                               |
| Input Threshold                | V <sub>IT</sub>     |         | 1.6  |     | V     | Input Threshold at rising edge                         |
|                                | V <sub>IT_HYS</sub> |         | 0.4  |     | V     | Input Threshold Hysteresis                             |
| High Level Input Voltage       | V <sub>IH</sub>     | 2       |      |     | V     |  |
| Low Level Input Voltage        | V <sub>IL</sub>     |         |      | 0.8 | V     |  |
| High Level Output Voltage      | V <sub>OH</sub>     | VDD-0.4 |      |     | V     | I <sub>OH</sub> = -4mA                                 |
| Low Level Output Voltage       | V <sub>OL</sub>     |         |      | 0.4 | V     | I <sub>OL</sub> = 4mA                                  |
| Output Impedance               | R <sub>out</sub>    |         | 50   |     | ohm   |  |
| Input Pull high or low Current | I <sub>pull</sub>   |         | 8    | 15  | uA    |  |
| Start Up Time after POR        | tr <sub>bs</sub>    |         | 10   |     | usec  |  |
| Common Mode Transient Immunity | CMTI                | ±200    | ±250 |     | kV/us | See <a href="#">Figure 5.6</a> , C <sub>L</sub> = 15pF |

## 5.2. Supply Current Characteristics – 5V

(VDD1=VDD2=5V ± 10%, Ta=-40°C to 125°C. Unless otherwise noted, Typical values are at VDD1=VDD2=5V, Ta = 25°C)

| Parameters     | Symbol     | Min | Typ  | Max  | Unit | Comments  |
|----------------|------------|-----|------|------|------|---|
| Supply current | IDD1(Q0)   |     | 0.64 | 0.96 | mA   | All Input 0V for NSi8210N0 or All Input at supply for NSi8210N1 |
|                | IDD2(Q0)   |     | 1.27 | 1.91 | mA   |   |
|                | IDD1(Q1)   |     | 1.66 | 2.49 | mA   | All Input at supply for NSi8210N0 or All Input 0V for NSi8210N1 |
|                | IDD2(Q1)   |     | 1.28 | 1.92 | mA   |   |
|                | IDD1(1M)   |     | 1.16 | 1.74 | mA   | All Input with 1Mbps,<br>CL=15pF                                |
|                | IDD2(1M)   |     | 1.33 | 2.00 | mA   |   |
|                | IDD1(10M)  |     | 1.17 | 1.76 | mA   | All Input with 10Mbps,<br>CL=15pF                               |
|                | IDD2(10M)  |     | 1.78 | 2.67 | mA   |   |
|                | IDD1(100M) |     | 1.34 | 2.01 | mA   | All Input with 100Mbps,<br>CL=15pF                              |
|                | IDD2(100M) |     | 6.16 | 9.24 | mA   |   |

## 5.3. Supply Current Characteristics – 3.3V

(VDD1=VDD2=3.3V ± 10%, Ta=-40°C to 125°C. Unless otherwise noted, Typical values are at VDD1=VDD2=3.3V, Ta = 25°C)

| Parameters     | Symbol     | Min | Typ  | Max  | Unit | Comments  |
|----------------|------------|-----|------|------|------|---|
| Supply current | IDD1(Q0)   |     | 0.6  | 0.9  | mA   | All Input 0V for NSi8210N0 or All Input at supply for NSi8210N1 |
|                | IDD2(Q0)   |     | 1.22 | 1.83 | mA   |   |
|                | IDD1(Q1)   |     | 1.62 | 2.43 | mA   | All Input at supply for NSi8210N0 or All Input 0V for NSi8210N1 |
|                | IDD2(Q1)   |     | 1.23 | 1.85 | mA   |   |
|                | IDD1(1M)   |     | 1.11 | 1.67 | mA   | All Input with 1Mbps,<br>CL=15pF                                |
|                | IDD2(1M)   |     | 1.26 | 1.89 | mA   |   |
|                | IDD1(10M)  |     | 1.12 | 1.68 | mA   | All Input with 10Mbps,<br>CL=15pF                               |
|                | IDD2(10M)  |     | 1.56 | 2.34 | mA   |   |
|                | IDD1(100M) |     | 1.17 | 1.76 | mA   | All Input with 100Mbps,<br>CL=15pF                              |
|                | IDD2(100M) |     | 4.48 | 6.72 | mA   |   |

## 5.4. Supply Current Characteristics – 2.5V

(VDD1=VDD2=2.5V ± 10%, Ta=-40°C to 125°C. Unless otherwise noted, Typical values are at VDD1=VDD2=2.5V, Ta = 25°C)



| Parameters     | Symbol     | Min | Typ  | Max  | Unit | Comments  |
|----------------|------------|-----|------|------|------|---|
| Supply current | IDD1(Q0)   |     | 0.58 | 0.87 | mA   | All Input 0V for NSi8210N0 or All Input at supply for NSi8210N1 |
|                | IDD2(Q0)   |     | 1.2  | 1.8  | mA   |   |
|                | IDD1(Q1)   |     | 1.6  | 2.4  | mA   | All Input at supply for NSi8210N0 or All Input 0V for NSi8210N1 |
|                | IDD2(Q1)   |     | 1.2  | 1.8  | mA   |   |
|                | IDD1(1M)   |     | 1.09 | 1.64 | mA   | All Input with 1Mbps,<br>CL=15pF                                |
|                | IDD2(1M)   |     | 1.23 | 1.85 | mA   |   |
|                | IDD1(10M)  |     | 1.10 | 1.65 | mA   | All Input with 10Mbps,<br>CL=15pF                               |
|                | IDD2(10M)  |     | 1.46 | 2.19 | mA   |   |
|                | IDD1(100M) |     | 1.07 | 1.61 | mA   | All Input with 100Mbps,<br>CL=15pF                              |
|                | IDD2(100M) |     | 3.72 | 5.58 | mA   |   |

## 5.5. Switching Characteristics – 5V

(VDD1=5V± 10%, VDD2=5V± 10%, Ta=-40°C to 125°C. Unless otherwise noted, Typical values are at VDD1 = 5V, VDD2 = 5V, Ta = 25°C)

| Parameters   | Symbol               | Min | Typ  | Max | Unit | Comments   |
|--|----------------------|-----|------|-----|------|--|
| Data Rate  | DR                   | 0   |      | 150 | Mbps |  |
| Minimum Pulse Width  | PW                   |     |      | 5.0 | ns   |  |
| Propagation Delay  | t <sub>PLH</sub>     | 2.5 | 6.54 | 15  | ns   | See <a href="#">Figure 5.7</a> , C <sub>L</sub> = 15pF |
|  | t <sub>PHL</sub>     | 2.5 | 8.30 | 15  | ns   | See <a href="#">Figure 5.7</a> , C <sub>L</sub> = 15pF |
| Pulse Width Distortion<br> t <sub>PHL</sub> - t <sub>PLH</sub> | PWD                  |     |      | 5.0 | ns   | See <a href="#">Figure 5.7</a> , C <sub>L</sub> = 15pF |
| Rising Time  | t <sub>r</sub>       |     |      | 5.0 | ns   | See <a href="#">Figure 5.7</a> , C <sub>L</sub> = 15pF |
| Falling Time   | t <sub>f</sub>       |     |      | 5.0 | ns   | See <a href="#">Figure 5.7</a> , C <sub>L</sub> = 15pF |
| Peak Eye Diagram Jitter  | t <sub>JIT(PK)</sub> |     | 350  |     | ps   |  |
| Channel-to-Channel Delay Skew                                  | t <sub>SK(c2c)</sub> |     |      | 2.5 | ns   |  |
| Part-to-Part Delay Skew  | t <sub>SK(p2p)</sub> |     |      | 5.0 | ns   |  |

## 5.6. Switching Characteristics – 3.3V

(VDD1=3.3V± 10%, VDD2=3.3V± 10%, Ta=-40°C to 125°C. Unless otherwise noted, Typical values are at VDD1 = 3.3V, VDD2 = 3.3V, Ta = 25°C)

| Parameters   | Symbol                | Min | Typ | Max | Unit | Comments   |
|--|-----------------------|-----|-----|-----|------|--|
| Data Rate  | DR                    | 0   |     | 150 | Mbps |  |
| Minimum Pulse Width  | PW                    |     |     | 5.0 | ns   |  |
| Propagation Delay  | t <sub>PLH</sub>      | 2.5 | 8.0 | 15  | ns   | See <a href="#">Figure 5.7</a> , C <sub>L</sub> = 15pF |
|  | t <sub>PHL</sub>      | 2.5 | 8.7 | 15  | ns   | See <a href="#">Figure 5.7</a> , C <sub>L</sub> = 15pF |
| Pulse Width Distortion<br> t <sub>PHL</sub> - t <sub>PLH</sub> | PWD                   |     |     | 5.0 | ns   | See <a href="#">Figure 5.7</a> , C <sub>L</sub> = 15pF |
| Rising Time  | t <sub>r</sub>        |     |     | 5.0 | ns   | See <a href="#">Figure 5.7</a> , C <sub>L</sub> = 15pF |
| Falling Time   | t <sub>f</sub>        |     |     | 5.0 | ns   | See <a href="#">Figure 5.7</a> , C <sub>L</sub> = 15pF |
| Peak Eye Diagram Jitter  | t <sub>JIT</sub> (PK) |     | 350 |     | ps   |  |
| Channel-to-Channel Delay Skew                                  | t <sub>SK</sub> (c2c) |     |     | 2.5 | ns   |  |
| Part-to-Part Delay Skew  | t <sub>SK</sub> (p2p) |     |     | 5.0 | ns   |  |

## 5.7. Switching Characteristics – 2.5V

(VDD1=2.5V± 10%, VDD2=2.5V± 10%, Ta=-40°C to 125°C. Unless otherwise noted, Typical values are at VDD1 = 2.5V, VDD2 = 2.5V, Ta = 25°C)

| Parameters   | Symbol                | Min | Typ | Max | Unit | Comments   |
|--|-----------------------|-----|-----|-----|------|--|
| Data Rate  | DR                    | 0   |     | 150 | Mbps |  |
| Minimum Pulse Width  | PW                    |     |     | 5.0 | ns   |  |
| Propagation Delay  | t <sub>PLH</sub>      | 2.5 | 9.0 | 15  | ns   | See <a href="#">Figure 5.7</a> , C <sub>L</sub> = 15pF |
|  | t <sub>PHL</sub>      | 2.5 | 9.3 | 15  | ns   | See <a href="#">Figure 5.7</a> , C <sub>L</sub> = 15pF |
| Pulse Width Distortion<br> t <sub>PHL</sub> - t <sub>PLH</sub> | PWD                   |     |     | 5.0 | ns   | See <a href="#">Figure 5.7</a> , C <sub>L</sub> = 15pF |
| Rising Time  | t <sub>r</sub>        |     |     | 5.0 | ns   | See <a href="#">Figure 5.7</a> , C <sub>L</sub> = 15pF |
| Falling Time   | t <sub>f</sub>        |     |     | 5.0 | ns   | See <a href="#">Figure 5.7</a> , C <sub>L</sub> = 15pF |
| Peak Eye Diagram Jitter  | t <sub>JIT</sub> (PK) |     | 350 |     | ps   |  |
| Channel-to-Channel Delay Skew                                  | t <sub>SK</sub> (c2c) |     |     | 2.5 | ns   |  |
| Part-to-Part Delay Skew  | t <sub>SK</sub> (p2p) |     |     | 5.0 | ns   |  |

5.8. Typical Performance Characteristics

Figure 5.1 NSi8210 VDD1 Supply Current vs Data Rate

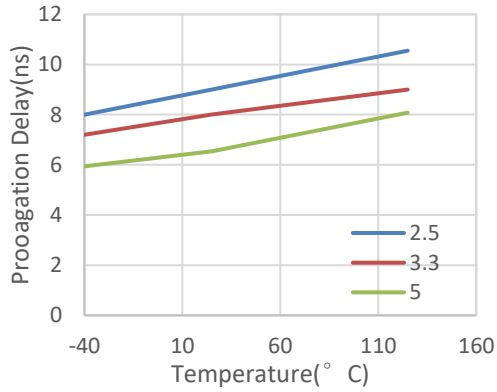


Figure 5.2 NSi8210 VDD2 Supply Current vs Data Rate

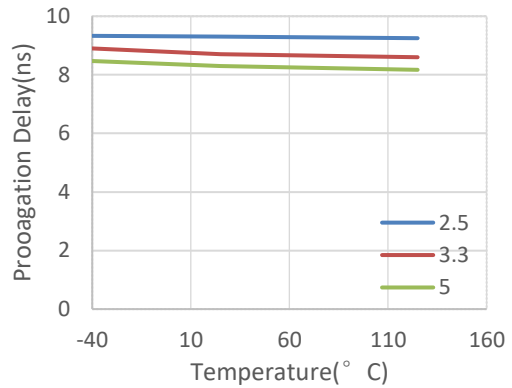


Figure 5.3 Rising Edge Propagation Delay Vs Temp

Figure 5.4 Falling Edge Propagation Delay Vs Temp

5.9. Parameter Measurement Information

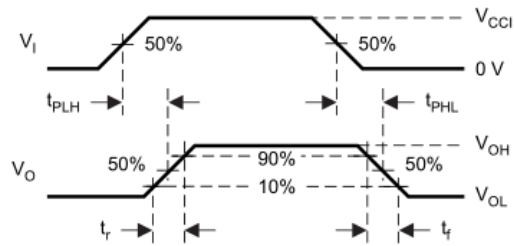
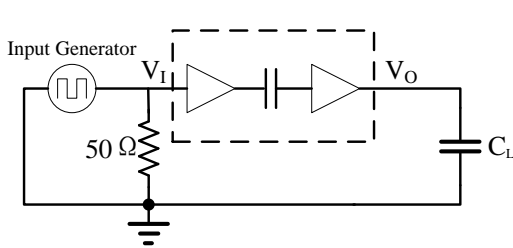


Figure 5.5 Switching Characteristics Test Circuit and Waveform

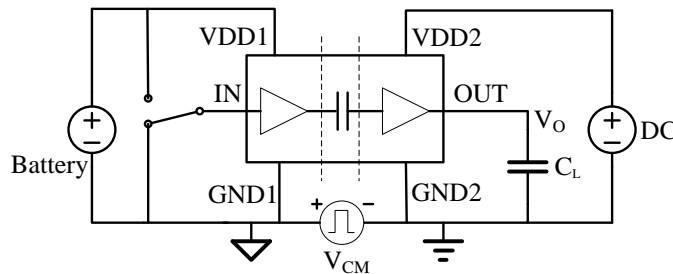


Figure 5.6 Common-Mode Transient Immunity Test Circuit

**6. High Voltage Feature Description**

**6.1. Insulation and Safety Related Specifications**

| <i>Parameters</i>                               | <i>Symbol</i> | <i>Value</i> |             |              | <i>Unit</i> | <i>Comments</i>   |
|---|---------------|--------------|-------------|--------------|-------------|---|
|   |               | <i>SOP8</i>  | <i>SOW8</i> | <i>SOW16</i> |             |   |
| Minimum External Air Gap (Clearance)            | L(I01)        | 4.0          | 8.0         | 8.0          | mm          | Shortest terminal-to-terminal distance through air                |
| Minimum External Tracking (Creepage)            | L(I02)        | 4.0          | 8.0         | 8.0          | mm          | Shortest terminal-to-terminal distance across the package surface |
| Minimum internal gap                            | DTI           | 20           |             |              | um          | Distance through insulation                                       |
| Tracking Resistance(Comparative Tracking Index) | CTI           | >400         | >600        | >600         | <b>V</b>    | DIN EN 60112 (VDE 0303-11); IEC 60112                             |
| Material Group                                  |               | II           | I           | I            |             |   |

6.2. DIN VDE V 0884-11 (VDE V 0884-11) :2017-01 Insulation Characteristics

| Description   | Test Condition  | Symbol      | Value     |           |           | Unit      |
|---|---|-------------|-----------|-----------|-----------|-----------|
|   |   |             | SOP8      | SOW8      | SOW16     |           |
| Installation Classification per DIN VDE 0110              |   |             |           |           |           |           |
| For Rated Mains Voltage $\leq 150V_{rms}$                 |   |             | I to IV   | I to IV   | I to IV   |           |
| For Rated Mains Voltage $\leq 300V_{rms}$                 |   |             | I to III  | I to IV   | I to IV   |           |
| For Rated Mains Voltage $\leq 400V_{rms}$                 |   |             | I to III  | I to IV   | I to IV   |           |
| Climatic Classification                                   |   |             | 10/105/21 | 10/105/21 | 10/105/21 |           |
| Pollution Degree per DIN VDE 0110, Table 1                |   |             | 2         | 2         | 2         |           |
| Maximum repetitive isolation voltage                      |   | $V_{IORM}$  | 565       | 2121      | 2121      | Vpeak     |
| Input to Output Test Voltage, Method B1                   | $V_{IORM} \times 1.5 = V_{pd(m)}$ ,<br>100% production test,<br>$t_{ini} = t_m = 1 \text{ sec}$ , $q_{pd} < 5 \text{ pC}$       | $V_{pd(m)}$ | 847       | /         | /         | Vpeak     |
|   | $V_{IORM} \times 1.875 = V_{pd(m)}$ ,<br>100% production test,<br>$t_{ini} = t_m = 1 \text{ sec}$ , $q_{pd} < 5 \text{ pC}$     |             | /         | 3977      | 3977      |           |
| Input to Output Test Voltage, Method A                    |   |             |           |           |           |           |
| After Environmental Tests Subgroup 1                      | $V_{IORM} \times 1.2 = V_{pd(m)}$ , $t_{ini} = 60 \text{ sec}$ , $t_m = 10 \text{ sec}$ , $q_{pd} < 5 \text{ pC}$               | $V_{pd(m)}$ | 678       | /         | /         | Vpeak     |
|   | $V_{IORM} \times 1.6 = V_{pd(m)}$ , $t_{ini} = 60 \text{ sec}$ , $t_m = 10 \text{ sec}$ , $q_{pd} < 5 \text{ pC}$               |             | /         | 3394      | 3394      |           |
| After Input and /or Safety Test Subgroup 2 and Subgroup 3 | $V_{IORM} \times 1.2 = V_{pd(m)}$ , $t_{ini} = 60 \text{ sec}$ , $t_m = 10 \text{ sec}$ , partial discharge $< 5 \text{ pC}$    | $V_{pd(m)}$ | 678       | 2545      | 2545      | Vpeak     |
| Maximum transient isolation voltage                       | $t = 60 \text{ sec}$  | VIOTM       | 5300      | 8000      | 8000      | Vpeak     |
| Maximum withstanding isolation voltage                    | $V_{TEST} = V_{ISO}$ , $t = 60 \text{ s}$ (qualification); $V_{TEST} = 1.2 \times V_{ISO}$ , $t = 1 \text{ s}$ (100%production) | VISO        | 3750      | 5000      | 5000      | $V_{RMS}$ |
| Maximum Surge Isolation Voltage                           | Test method per IEC60065, 1.2/50us waveform, $V_{TEST} = V_{IOSM} \times 1.3$   | VIOSM       | 5384      |           |           | Vpeak     |
|   | Test method per IEC60065, 1.2/50us  |             |           | 6250      | 6250      | Vpeak     |

|   | waveform,<br>VTEST=VIOSM×1.6  |     |            |            |            |          |
|---|---|-----|------------|------------|------------|----------|
| Isolation resistance                    | $V_{IO}=500V$ at $T_{amb}=T_s$  | RIO | $>10^9$    | $>10^9$    | $>10^9$    | $\Omega$ |
|   | $V_{IO}=500V$<br>at $100^\circ C \leq T_{amb} \leq 125^\circ C$                               |     | $>10^{11}$ | $>10^{11}$ | $>10^{11}$ | $\Omega$ |
| Isolation capacitance                   | $f = 1MHz$  | CIO | 0.6        | 0.6        | 0.6        | pF       |
| Input capacitance                       |   | CI  | 2          | 2          | 2          | pF       |
| Total Power Dissipation at 25°C         |   | Ps  | 856        | 1483       | 1324       | mW       |
| Safety input, output, or supply current | $\theta_{JA} = 146.1^\circ C/W$ , $V_I = 5.5 V$ ,<br>$T_J = 150^\circ C$ , $T_A = 25^\circ C$ | Is  | 156        |            |            | mA       |
|   | $\theta_{JA} = 84.3^\circ C/W$ , $V_I = 5.5 V$ ,<br>$T_J = 150^\circ C$ , $T_A = 25^\circ C$  |     |            | 269.6      |            |          |
|   | $\theta_{JA} = 94.4^\circ C/W$ , $V_I = 5.5 V$ ,<br>$T_J = 150^\circ C$ , $T_A = 25^\circ C$  |     |            |            | 240.8      |          |
| Case Temperature                        |   | Ts  | 150        | 150        | 150        | °C       |

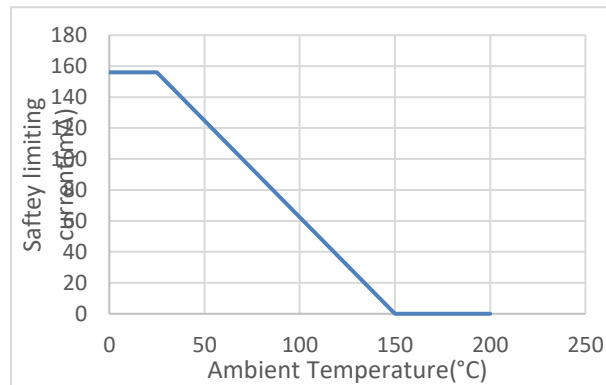


Figure 6.1 NSi8210N-DSPR Thermal Derating Curve, Dependence of Safety Limiting Values with Case Temperature per DIN VDE V 0884-11

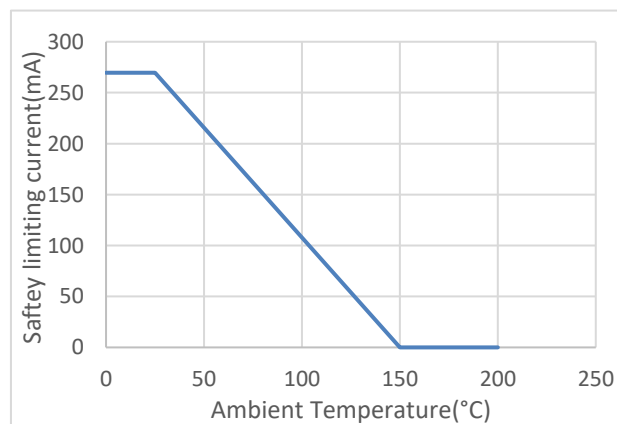


Figure 6.2 NSi8210W-DSWVR Thermal Derating Curve, Dependence of Safety Limiting Values with Case Temperature per DIN VDE V 0884-11

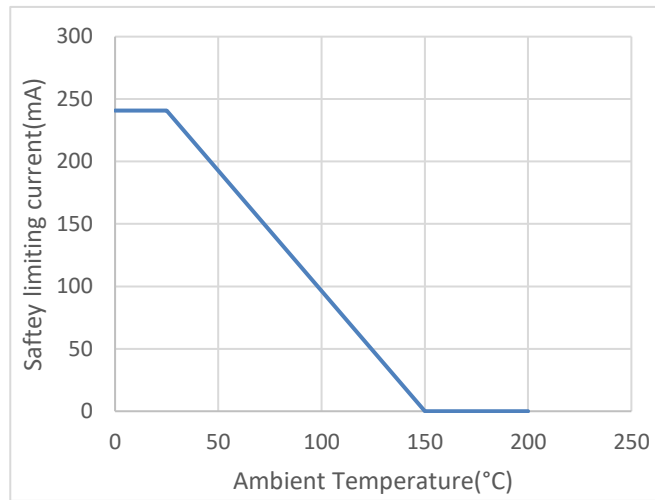


Figure 6.3 NSi8210W-DSWR Thermal Derating Curve, Dependence of Safety Limiting Values with Case Temperature per DIN VDE V 0884-11

## 6.3. Regulatory Information

The NSi8210N are approved by the organizations listed in table.

| <i>CUL</i>  |   | <i>VDE</i>   | <i>CQC</i>  |
|---|---|--|---|
| UL 1577 Component Recognition Program <sup>1</sup>        | Approved under CSA Component Acceptance Notice 5A         | DIN VDE V 0884-11:2017-01 <sup>2</sup>   | Certified by CQC11-471543-2012<br>GB4943.1-2011                 |
| Single Protection, 3750V <sub>rms</sub> Isolation voltage | Single Protection, 3750V <sub>rms</sub> Isolation voltage | Basic Insulation<br>565V <sub>peak</sub> ,<br>V <sub>IOSM</sub> =5384V <sub>peak</sub> | Basic insulation at 400V <sub>rms</sub> (565V <sub>peak</sub> ) |
| File (E500602)  | File (E500602)  | File (pending)   | File (CQC20001264940)   |

The NSi8210W-DSWVR are approved by the organizations listed in table.

| <i>CUL</i>  |   | <i>VDE</i>   | <i>CQC</i>   |
|---|---|--|--|
| UL 1577 Component Recognition Program <sup>1</sup>        | Approved under CSA Component Acceptance Notice 5A         | DIN VDE V 0884-11(VDE V 0884-11):2017-01 <sup>2</sup>  | Certified by CQC11-471543-2012<br>GB4943.1-2011                        |
| Single Protection, 5000V <sub>rms</sub> Isolation voltage | Single Protection, 5000V <sub>rms</sub> Isolation voltage | Reinforced Insulation<br>2121V <sub>peak</sub> ,<br>V <sub>IOSM</sub> =6250V <sub>peak</sub> | Reinforced insulation at 1500V <sub>rms</sub> (2121V <sub>peak</sub> ) |
| File (pending)  | File (pending)  | File (5024579-4880-0002 / 276211)  | File (CQC20001264938 )   |

The NSi8210W-DSWR are approved by the organizations listed in table.

| <i>CUL</i>  |   | <i>VDE</i>   | <i>CQC</i>   |
|---|---|--|--|
| UL 1577 Component Recognition Program <sup>1</sup>        | Approved under CSA Component Acceptance Notice 5A         | DIN VDE V 0884-11(VDE V 0884-11):2017-01 <sup>2</sup>  | Certified by CQC11-471543-2012<br>GB4943.1-2011                        |
| Single Protection, 5000V <sub>rms</sub> Isolation voltage | Single Protection, 5000V <sub>rms</sub> Isolation voltage | Reinforced Insulation<br>2121V <sub>peak</sub> ,<br>V <sub>IOSM</sub> =6250V <sub>peak</sub> | Reinforced insulation at 1500V <sub>rms</sub> (2121V <sub>peak</sub> ) |
| File (pending)  | File (pending)  | File (5024579-4880-0002 / 276211)  | File (CQC20001264939)  |

## 7. Function Description

### 7.1. Overview

The NSi8210 is a single-channel digital isolator based on a capacitive isolation barrier technique. The digital signal is modulated with RF carrier generated by the internal oscillator at the Transmitter side. Then it is transferred through the capacitive isolation barrier and demodulated at the Receiver side.

NSi8210 is a high reliability single channel digital isolator with AEC-Q100(Grade 1) qualified, it's certified by UL1577 and support 3.75kVrms insulation withstand voltage, while providing high electromagnetic immunity and low emissions at low power consumption. The data rate of NSi8210 is up to 150Mbps, and the common-mode transient immunity (CMTI) is up to 200kV/us. NSi8210 provides



default output level configuration when the input power is lost. Wide supply voltage of NSi8210 supports to connect with most digital interface directly, easy to do the level shift.

NSi8210 has a default output status when VDDIN is unready and VDDOUT is ready as shown in Table 7.1, which helps for diagnosis when power is missing at the transmitter side. The other outputs follow the same status with the input A within 1us after powering up respectively.

Table 7.1 Output status vs. power status with interlock function

| Input          | VDD1 status | VDD2 status | Output | Comment   |
|----------------|-------------|-------------|--------|---|
| H <sup>1</sup> | Ready       | Ready       | H      | Normal operation.   |
| L <sup>2</sup> | Ready       | Ready       | L      |   |
| X <sup>3</sup> | Unready     | Ready       | L<br>H | The output follows the same status with the input within 20us after input side VDD1 is powered on.  |
| X              | Ready       | Unready     | X      | The output follows the same status with the input within 20us after output side VDD2 is powered on. |

Note: <sup>1</sup>H=Logic high; <sup>2</sup>L=Logic low; <sup>3</sup>X=Logic low or logic high

## 7.2. OOK Modulation

NSi8210 is based on a capacitive isolation barrier technique and the digital signal is modulated with RF carrier generated by the internal oscillator at the transmitter side, as shown in Figure 7.1 & Figure 7.2, then it is transferred through the capacitive isolation barrier and demodulated at the receiver side. The modulation uses OOK modulation technique with key benefits of high noise immunity and low radiation EMI.

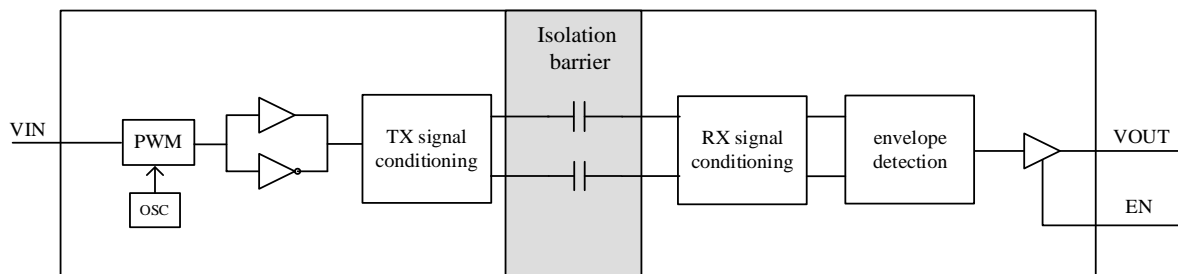


Figure 7.1 Single Channel Function Block Diagram

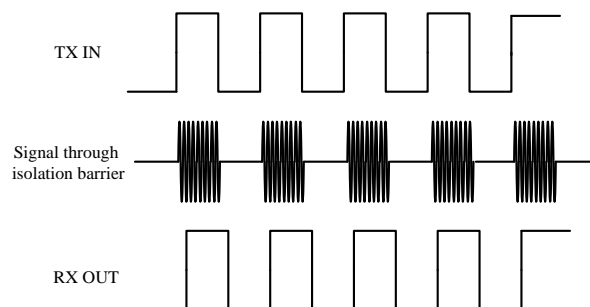


Figure 7.2 OOK Modulation

## 8. Application Note

### 8.1. Typical Application Circuit

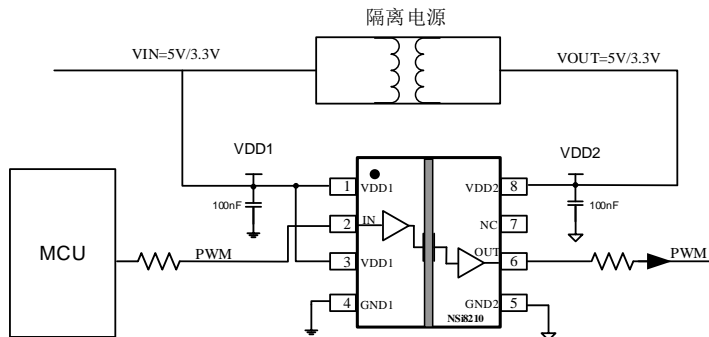


Figure 8.1 Typical PWM isolation circuit

### 8.2. PCB Layout

NSi8210 requires a 0.1  $\mu\text{F}$  bypass capacitor between VDD1 and GND1, VDD2 and GND2. The capacitor should be placed as close as possible to the package. Figure 8.2 to Figure 8.3 show the recommended PCB layout, make sure the space under the chip should keep free from planes, traces, pads and via. To enhance the robustness of a design, the user may also include resistors (50–300  $\Omega$ ) in series with the inputs and outputs if the system is excessively noisy. The series resistors also improve the system reliability such as latch-up immunity.

The typical output impedance of an isolator driver channel is approximately 50 $\Omega$ ,  $\pm 40\%$ . When driving loads where transmission line effects will be a factor, output pins should be appropriately terminated with controlled impedance PCB traces.

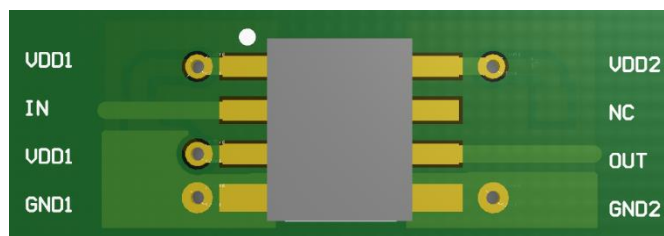


Figure8.2 Recommended PCB Layout — Top Layer



Figure8.3 Recommended PCB Layout — Bottom Layer

8.3. High Speed Performance



Figure 8.4 NSi8210N Eye diagram of output signal at 200Mbps

8.4. Typical Supply Current Equations

The typical supply current of NSi8210 can be calculated using below equations.  $I_{DD1}$  and  $I_{DD2}$  are typical supply currents measured in mA,  $f$  is data rate measured in Mbps,  $C_L$  is the capacitive load measured in pF

NSi8210:

$$I_{DD1} = 0.6 * a1 + 1.25 * b1 + 1.1 * c1.$$

$$I_{DD2} = 0.9 * a1 + 1.85 * b1 + VDD1 * f * C_L * c1 * 10^{-9}$$

Where  $a1$  is the channel number of low inputs at side 1,  $b1$  is the channel number of high inputs at side 1,  $c1$  is the channel number of switch signal inputs at side 1.

9. Package Information

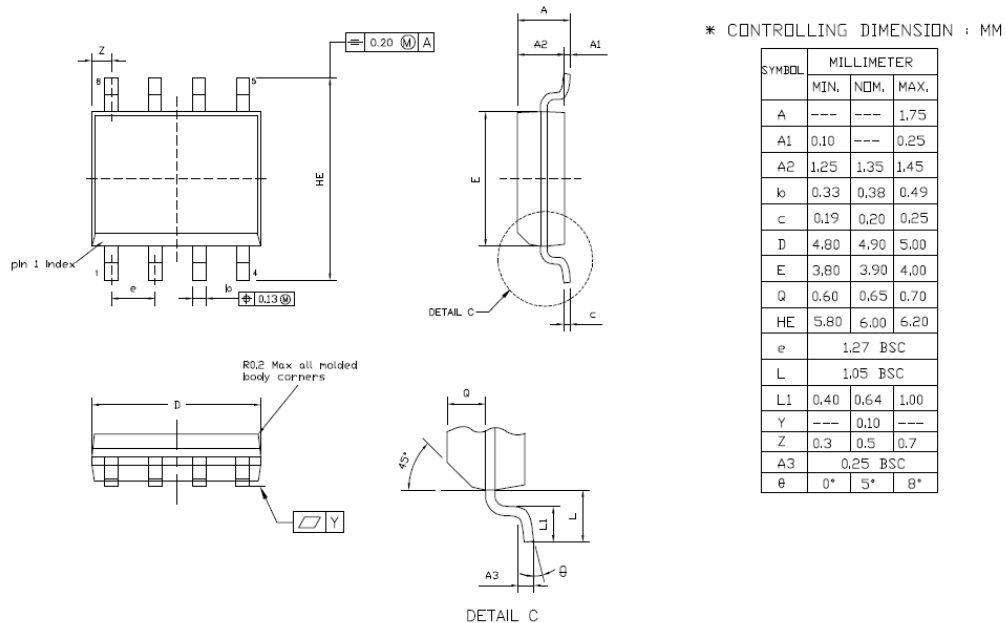


Figure 9.1 SOP8 Package Shape and Dimension in millimeters and (inches)

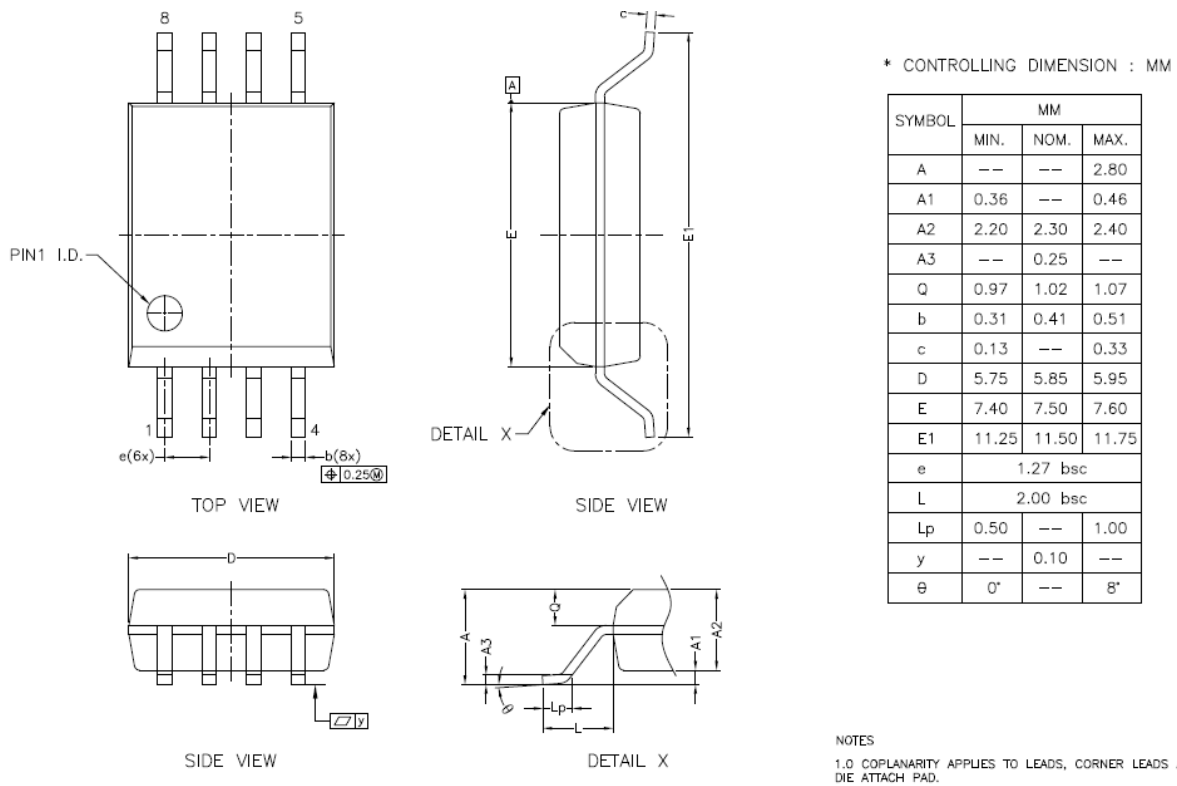


Figure 9.2 SOW8 Package Shape and Dimension in millimeters and (inches)

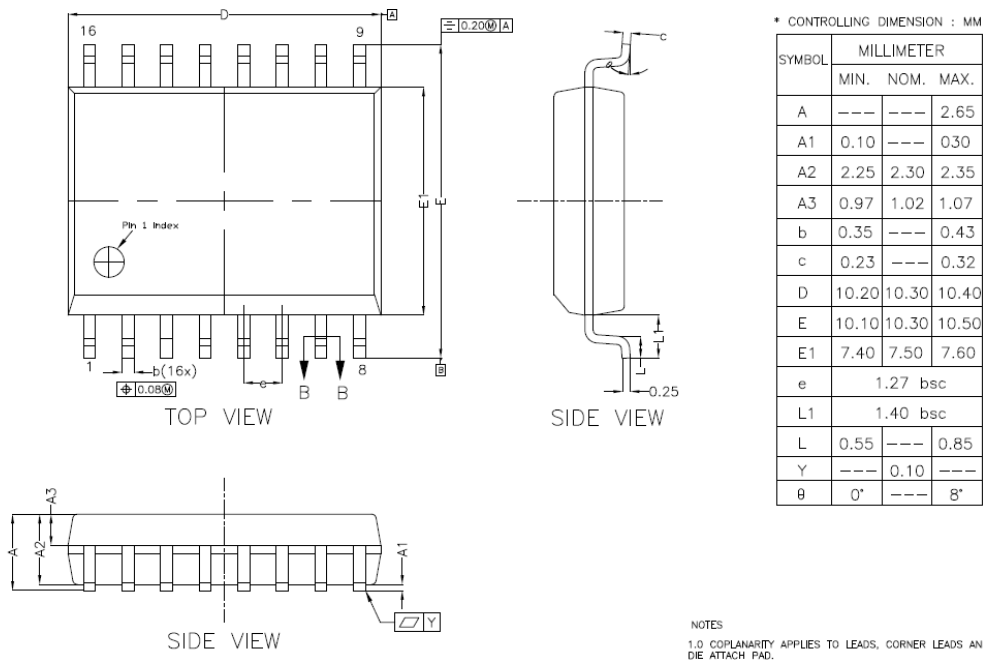
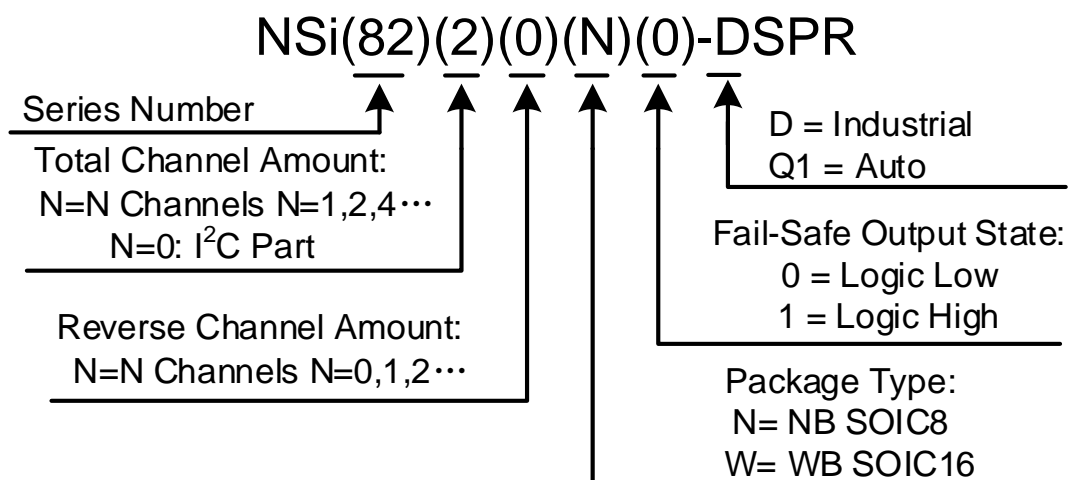


Figure 9.2 SOW16 Package Shape and Dimension in millimeters and (inches)

10. Ordering Information

| Part Number      | Isolation Rating (kV) | Number of side 1 inputs | Number of side 2 inputs | Max Data Rate (Mbps) | Default Output State | Temperature  | MSL | Package Type   | Package Drawing | SPQ  |
|------------------|-----------------------|-------------------------|-------------------------|----------------------|----------------------|--------------|-----|----------------|-----------------|------|
| NSI8210N0-DSPR   | 3.75                  | 1                       | 0                       | 150                  | Low                  | -40 to 125°C | 1   | SOP8 (150mil)  | SOP8            | 2500 |
| NSI8210N1-DSPR   | 3.75                  | 1                       | 0                       | 150                  | High                 | -40 to 125°C | 1   | SOP8 (150mil)  | SOP8            | 2500 |
| NSI8210N0-Q1SPR  | 3.75                  | 1                       | 0                       | 150                  | Low                  | -40 to 125°C | 1   | SOP8 (150mil)  | SOP8            | 2500 |
| NSI8210N1-Q1SPR  | 3.75                  | 1                       | 0                       | 150                  | High                 | -40 to 125°C | 1   | SOP8 (150mil)  | SOP8            | 2500 |
| NSI8210W0-DSWVR  | 5                     | 1                       | 0                       | 150                  | Low                  | -40 to 125°C | 3   | SOP8 (300mil)  | SOW8            | 1000 |
| NSI8210W1-DSWVR  | 5                     | 1                       | 0                       | 150                  | High                 | -40 to 125°C | 3   | SOP8 (300mil)  | SOW8            | 1000 |
| NSI8210W0-Q1SWVR | 5                     | 1                       | 0                       | 150                  | Low                  | -40 to 125°C | 3   | SOP8 (300mil)  | SOW8            | 1000 |
| NSI8210W1-Q1SWVR | 5                     | 1                       | 0                       | 150                  | High                 | -40 to 125°C | 3   | SOP8 (300mil)  | SOW8            | 1000 |
| NSI8210W0-DSWR   | 5                     | 1                       | 0                       | 150                  | Low                  | -40 to 125°C | 2   | SOW16 (300mil) | SOW16           | 1000 |
| NSI8210W1-DSWR   | 5                     | 1                       | 0                       | 150                  | High                 | -40 to 125°C | 2   | SOW16 (300mil) | SOW16           | 1000 |
| NSI8210W0-Q1SWR  | 5                     | 1                       | 0                       | 150                  | Low                  | -40 to 125°C | 2   | SOW16 (300mil) | SOW16           | 1000 |
| NSI8210W1-Q1SWR  | 5                     | 1                       | 0                       | 150                  | High                 | -40 to 125°C | 2   | SOW16 (300mil) | SOW16           | 1000 |

Part Number Rule:



## 11. Documentation Support

| <i>Part Number</i> | <i>Product Folder</i>      | <i>Datasheet</i>           | <i>Technical Documents</i> | <i>Isolator selection guide</i> |
|--------------------|----------------------------|----------------------------|----------------------------|---------------------------------|
| NSi8210            | <a href="#">Click here</a> | <a href="#">Click here</a> | <a href="#">Click here</a> | <a href="#">Click here</a>      |

## 12. Tape and Reel Information

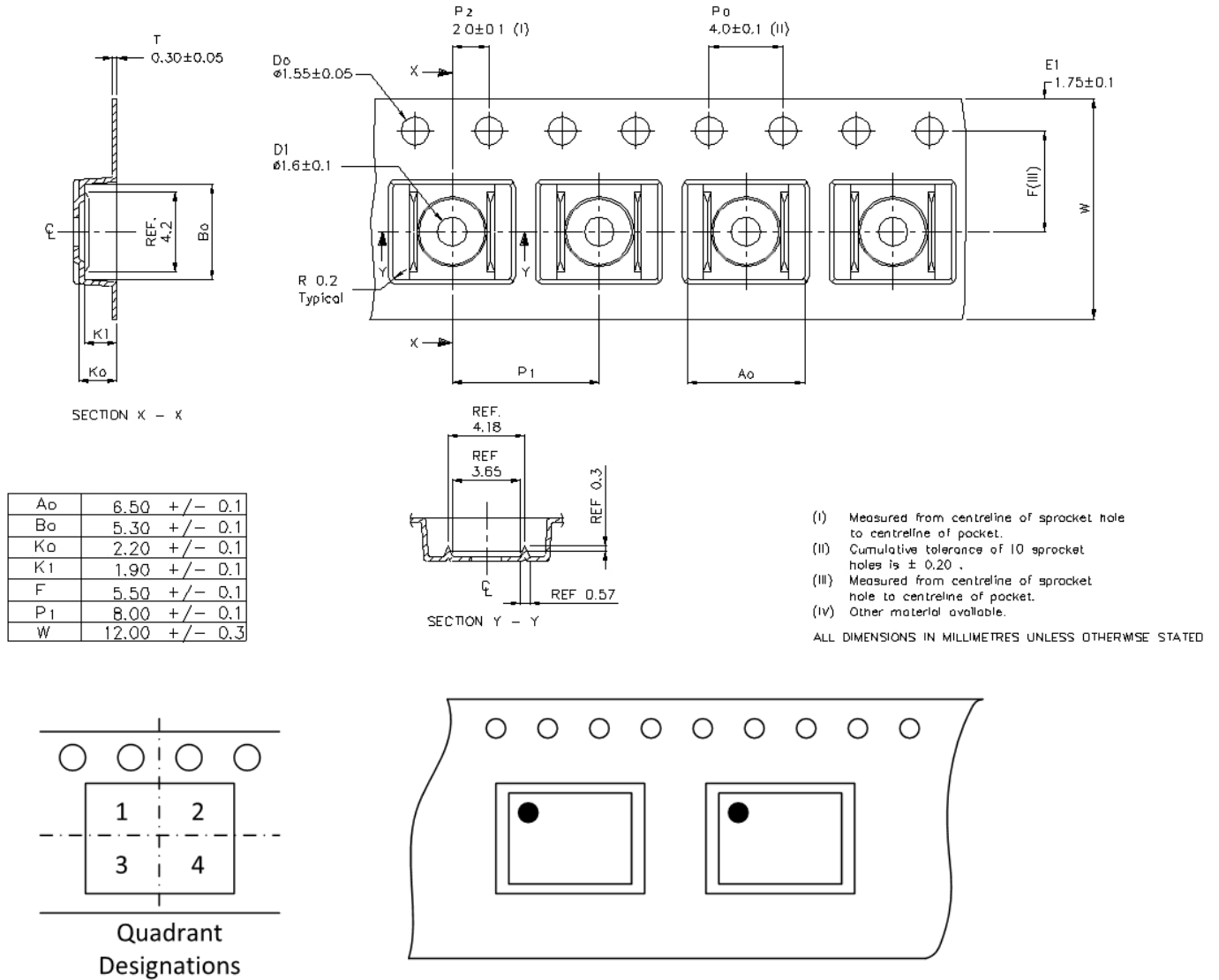


Figure 12.1 Tape and Reel Information of SOP8

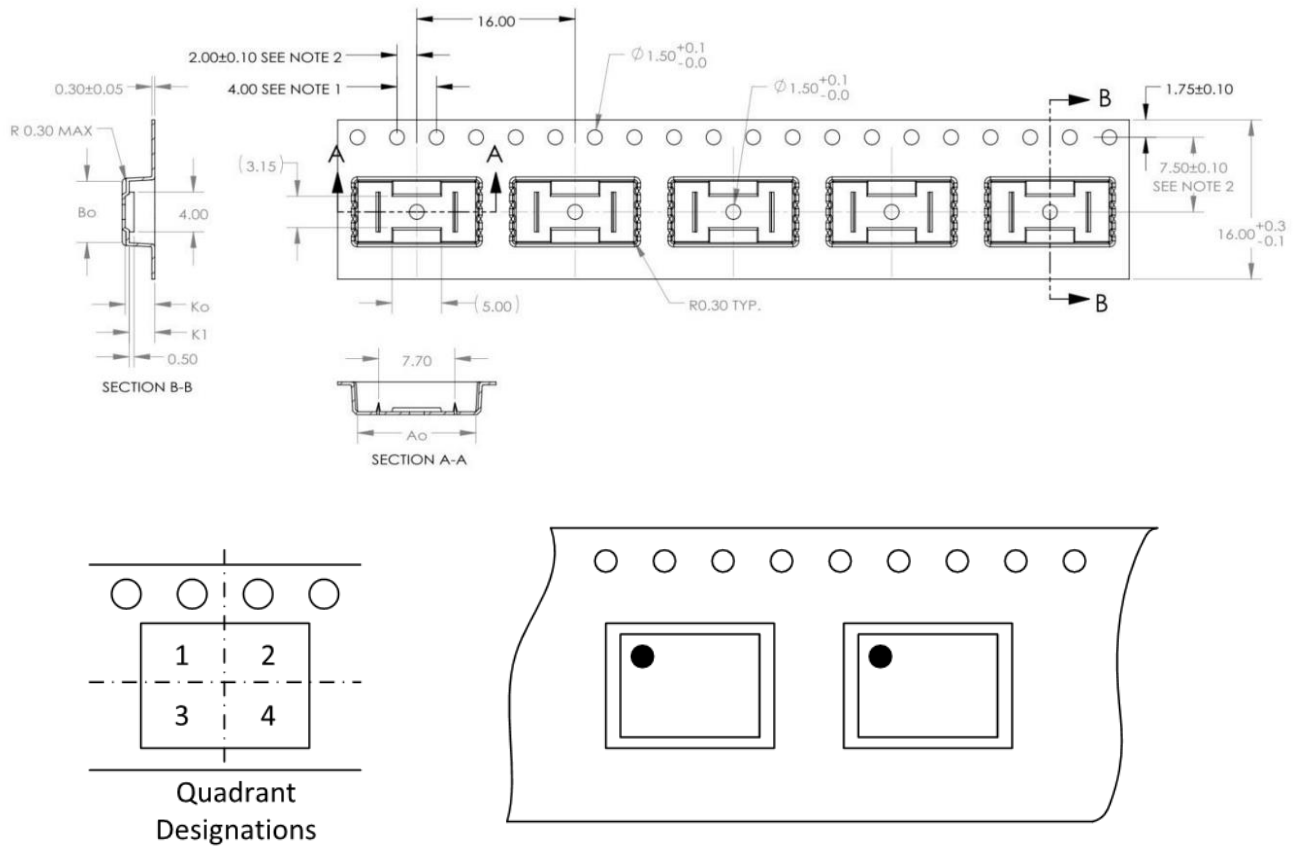
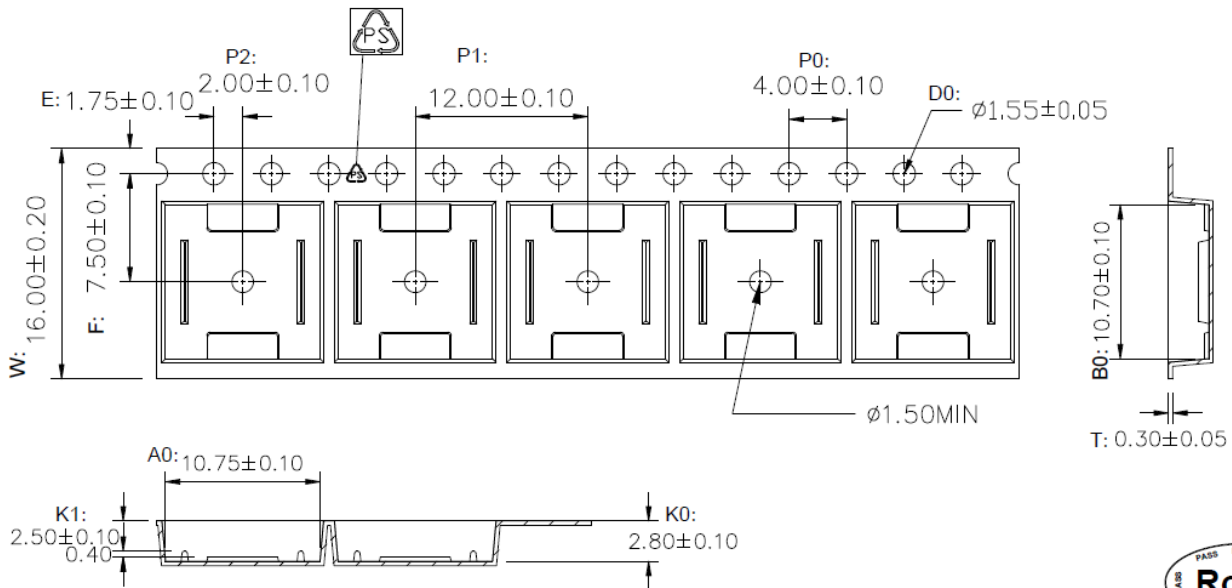
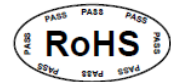


Figure 12.2 Tape and Reel Information of SOW8





1. 10 sprocket hole pitch cumulative tolerance  $\pm 0.20$  .
2. Carrier camber is within 1 mm in 250 mm.
3. Material : Black Conductive Polystyrene Alloy .
4. All dimensions meet EIA-481 requirements.
5. Thickness :  $0.30 \pm 0.05$ mm.
6. Packing length per 22" reel : 378 Meters.(復巻 N=122)
7. Component load per 13" reel : 1000 pcs.
8. Surface resistivity :  $10^5 \sim 10^{10} \Omega/\square$



|    |            |
|----|------------|
| W  | 16.00±0.20 |
| A0 | 10.75±0.10 |
| B0 | 10.70±0.10 |
| K0 | 2.80±0.10  |
| K1 | 2.50±0.10  |

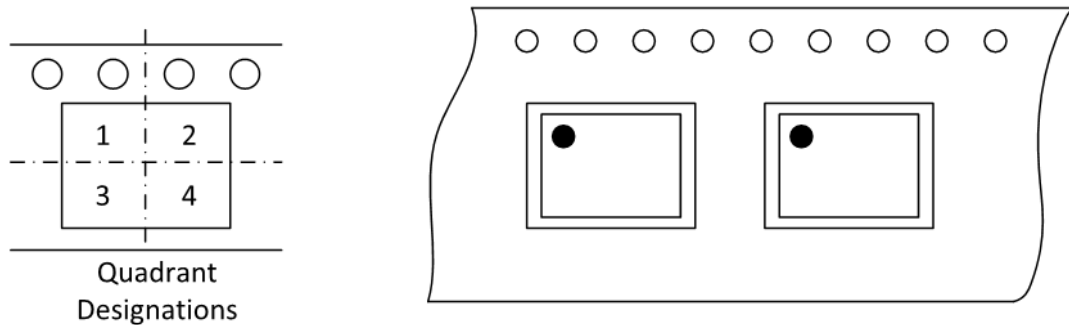


Figure 12.2 Tape and Reel Information of SOW16

### 13. Revision History

| Revision | Description      | Date      |
|----------|------------------|-----------|
| 1.0      | Initial Version. | 2020/12/7 |
|          |                  |           |
|          |                  |           |